flip chip land gid array package; no leads; body: 3.2 x 2.2 x 0.774 mm, 3-pad

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21 March 2023

Package information

1. Package summary

Terminal position code B (bottom)

Package type descriptive code FCLGA3

Package type industry code FCLGA3

Package style descriptive code FCP (flip chip package)

Package body material type X (other)

JEDEC package outline code MO-303 compatible

Mounting method type S (surface mount)

Number of package outline detail graphic

references

Issue date13-3-2023Manufacturer package codeSOT8073Footprint dimensions (mm)3.5 x 2.5Footprint area (mm²)8.75

Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	-	-	2.2	-	mm
Е	package width	-	-	3.2	-	mm
A	seated height	0.674	-	0.774	0.874	mm
е	nominal pitch	-	-	1.195	-	mm
e ₁	minimal pitch	-	-	1.695	-	mm
n ₂	actual quantity of termination	-	-	3	-	



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2. Package outline

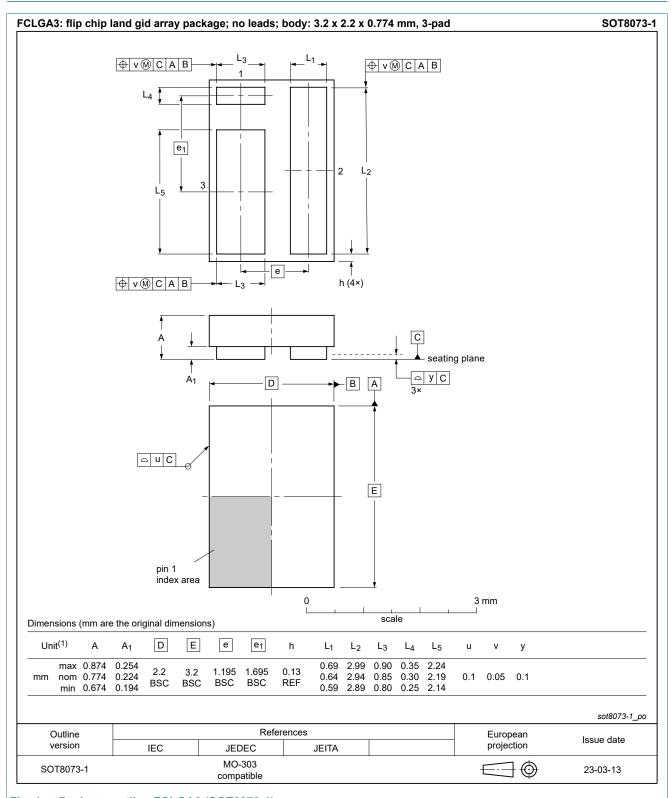
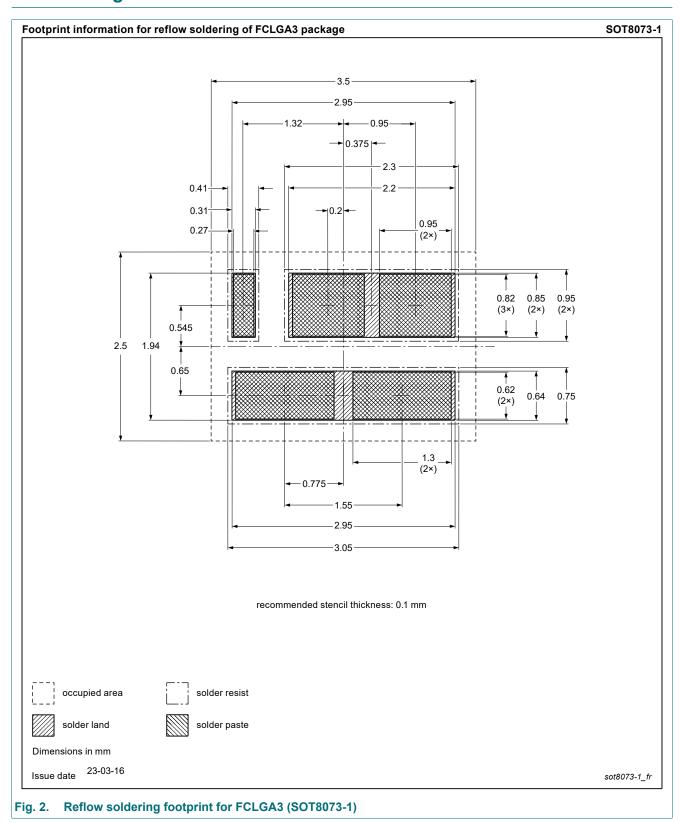


Fig. 1. Package outline FCLGA3 (SOT8073-1)

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3. Soldering



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SOT8073-1

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